

Title (en)

DEVICE FOR GRIPPING A SEMICONDUCTOR PLATE THROUGH A TRANSFER OPENING, USING THE CLOSURE OF THE OPENING

Title (de)

GERÄT ZUR HANDHABUNG VON HALBLEITERSCHEIBEN ZUM DURCHQUEREN EINER ÖFFNUNG BEI NUTZUNG DER VERSCHLUSSVORRICHTUNG DER ÖFFNUNG

Title (fr)

DISPOSITIF PERMETTANT LA PREHENSION D'UNE PLAQUE DE SEMI-CONDUCTEUR A TRAVERS UNE OUVERTURE DE TRANSFERT, UTILISANT L'OBTURATEUR DE L'OUVERTURE

Publication

**EP 1610927 A2 20060104 (FR)**

Application

**EP 03813172 A 20031212**

Priority

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- US 43351602 P 20021213

Abstract (en)

[origin: WO2004054755A2] The invention concerns a device (1) for gripping, through a transfer station opening (10) for a semiconductor plate processing installation, at least one semiconductor plate (11) having the shape of a disc, housed inside a container (14) of semiconductor plates located on one first side (15) of said opening, from a space (16) located on a second side (17) of said opening opposite the first side. Said device comprises: a mobile closure (1) capable of moving between a first position closing said opening, and a second position releasing said opening allowing access inside the container; means for moving (18) said closure between said first and second positions thereof, said displacement being located at least partly in a plane substantially parallel to the plane of said opening. Said device is characterized in that it comprises: means for gripping (2) at least one semiconductor plate (11), capable of partly penetrating inside said container beneath a plate and of gripping the latter by its peripheral part; means for moving (3) said gripping means from said space located on the second side of the opening towards the first side, or inversely; means for connecting (4) to said closure said means for moving the gripping means.

IPC 1-7

**B23Q 7/00**

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2004054755A2

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